

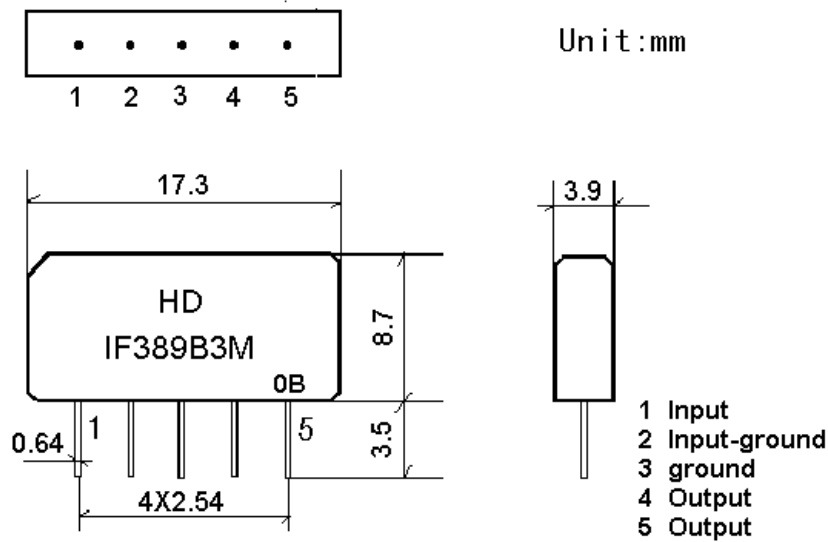
1. SCOPE

The SAW filter series have broad line up products meeting all broadcast standard including NTSC, PAL and SECAM systems. These filters are composed of two interdigital transducers on a single-crystal, piezoelectrical chip. They are used in electronic equipments such as TV and so on.

2. Construction

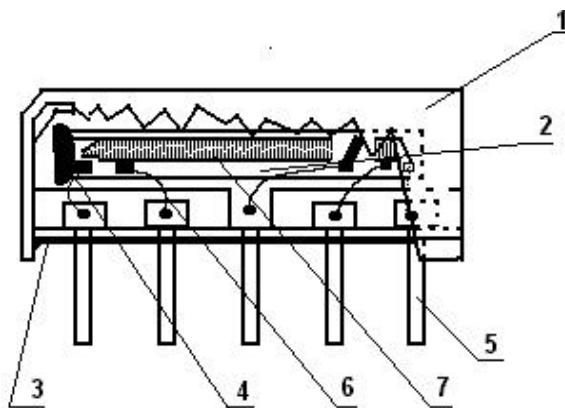
2.1 Dimension and materials

Type: IF389B3M



0: year(0,1,2,3,4,5,6,7,8,9)

B:product in this quarter(A:1~3,B:4~6,C:7~9,D:10~12)



Components	Materials
1.Outer casing	PPS
2.Substrate	Lithium niobate
3.Base	Epoxy resin
4.Absorber	Epoxy resin
5.Lead	Cu alloy+Au plate
6.Bonding wire	AlSi alloy
7.Electrode	Al

3.2 Electrical Characteristics

Source impedance $Z_s=50$
 Load impedance $Z_L=2k //3pF$ $T_A=25$

Items	Freq	Min	typ	max	
Insertion attenuation Reference level	37.40MHz	15.2	17.2	19.2	dB
Relative attenuation	38.90MHz	4.1	5.6	7.1	dB
	34.47MHz	1.6	3.1	4.6	dB
	32.40MHz	18.4	20.4	22.4	dB
	33.40MHz	17.3	19.3	-	dB
	30.90MHz	43.0	57.0		dB
	31.90MHz	38.0	48.0		dB
	40.40MHz	42.0	55.0		dB
	41.40MHz	41.0	54.0		dB
Sidelobe	25.00~30.90MHz	38.0	47.0		dB
	40.40~45.00MHz	35.0	43.0		dB
Reflected wave signal suppression 1.2 μ s..6.0 μ s after main pulse (test pulse 250ns, carrier frequency 37.4MHz)		40.0	50.0		dB
Feedthrough signal suppression 1.2 μ s..1.1 μ s before main pulse (test pulse 250ns, carrier frequency 37.4MHz)		42.0	52.0	-	dB
Group delay predistortion (reference frequency 38.90 MHz)					
36.90 MHz	-	-55	-	ns	
34.47 MHz	-	45	-	ns	
Impedance at 37.40 MHz: Input: $Z_{in} = R_{in} // C_{in}$ Output $Z_{out}=R_{out} // C_{out}$		-	2.2//11.9 3.8 //2.8	-	k //pF k //pF
Temperature coefficient			-72		Ppm/k

3.3 Environmental Performance Characteristics

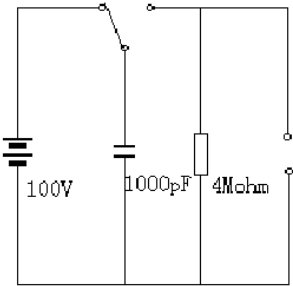
Item Test condition	Allowable change of absolute Level at center frequency (dB)
High temperature test 70 1000H	< 1.0
Low temperature test -40 1000H	< 1.0
Humidity test 40 90-95% 1000H	< 1.0
Thermal shock -20 ==25 ==80 20 cycle 30M 10M 30M	< 1.0
Solder temperature test Sold temp.260 for 10 sec.	< 1.0

Soldering Immerse the pins melt solder at 260 +5/-0 for 5 sec.	More then 95% of total area of the pins should be covered with solder
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3.4 Mechanical Test

Item Test condition	Allowable change of absolute Level at center frequency(dB)
Vibration test 600-3300rpm amplitude 1.5mm 3 directions 2 H each	<1.0
Drop test On maple plate from 1 m high 3 times	<1.0
Lead pull test Pull with 1 kg force for 30 seconds	<1.0
Lead bend test 90° bending with 500g weigh 2 times	<1.0

3.5 Voltage Discharge Test

Item Test condition	Allowable change of absolute Level at center frequency (dB)
Surge test Between any two electrode 	<1.0